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Hung-Yin Tsai, National Tsing Hua University

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Chair: Ben-Je Lwo, National Defense University
Irving Lee, UL LLC

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TW0055	Upon Human's Unknown, Can AI Help to Address Uncertainty? A Practice on Package Substrate AOI Defect Detection...42	Wong-Shian Huang	ASE GROUP
TW0037	Anti-Corrosion Capacity Validation for Anti-Sulfur Type Electronic Passive Components by Way of Various Flower-of-Sulfur (FoS) Methodologies...46	Dem Lee	Integrated Service Technology, Inc.
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